

Title (en)

CHIP PACKAGING MODULE AND PACKAGING METHOD THEREOF, AND ELECTRONIC DEVICE WITH CHIP PACKAGING MODULE

Title (de)

CHIPVERPACKUNGSMODUL UND VERPACKUNGSVERFAHREN DAVON, UND ELEKTRONISCHE VORRICHTUNG MIT CHIPVERPACKUNGSMODUL

Title (fr)

MODULE D'ENCAPSULATION DE PUCE ET SON PROCÉDÉ D'ENCAPSULATION , ET DISPOSITIF ÉLECTRONIQUE AVEC MODULE D'ENCAPSULATION DE PUCE

Publication

EP 4089917 A4 20240424 (EN)

Application

EP 20896027 A 20200506

Priority

- CN 201911227573 A 20191204
- CN 2020088704 W 20200506

Abstract (en)

[origin: EP4089917A1] Disclosed are a chip packaging module and a packaging method thereof, and an electronic device with the chip packaging module. The chip packaging module includes: a chip (15); a package substrate (10), which faces the chip (15), a cavity being formed therebetween; a first packaging layer (17) for packaging the chip (15) on the package substrate (10); and a second packaging layer (19), which covers an outer side of the first packaging layer (17), wherein the first packaging layer (17) includes an extension part extending outwards in the transverse direction of the package substrate (10), a lower side of the extension part covers an upper side of the package substrate (10), and an end part of the second packaging layer (19) is in surface contact with an upper side of the extension part.

IPC 8 full level

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CPC (source: CN EP)

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Citation (search report)

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- [Y] US 2003062533 A1 20030403 - YEE LOW HONG [SG], et al
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Designated contracting state (EPC)

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